

Docket No.: 27-017

PATENT

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application of:	Byung Tai Do, et al.	:	Confirmation No.:	8877
Serial No.:	10/825,910	:	Art Unit:	2818
Filed:	4/16/2004	:	Examiner:	Tu Tu V Ho
For:	THERMALLY ENHANCED STACKED DIE PACKAGE AND FABRICATION METHOD			

Mail Stop AF
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

**AMENDMENT AFTER FINAL REJECTION
UNDER 37 C.F.R. §1.116**

Sir/Madam:

The following Amendment and Remarks are submitted under 37 C.F.R. §1.116 in response to the Office Action mailed June 17, 2005, following the amendment format set forth under 37 CFR §1.121. After this introductory section, there are Amendments to the Specification and Drawings and then Remarks, each starting on a separate page.

Amendments to the Specification consist of corrections of typographical errors in the Best Mode For Carrying Out the Invention. Drawing amendments consist of corrections of typographical errors in FIGs. 6-8. The pending claims are incorporated in a complete listing of the claims.